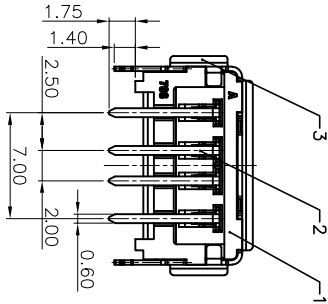
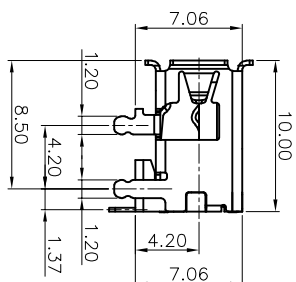
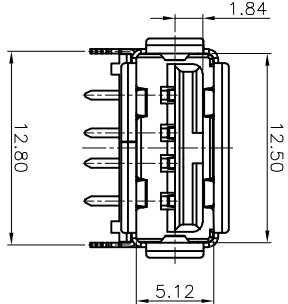
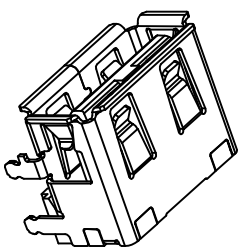
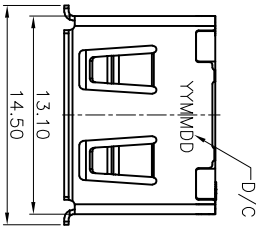


PIN DEFINE TABLE:

PIN No.	Signal Name
1	VBUS
2	D-
3	D+
4	GND

RECOMMENDED PCB LAYOUT (TOP VIEW)
TOLERANCES ±0.05; THICKNESS=1.60

- NOTES:
1. MATERIAL:
- 1.1 HOUSING: LCP, 30%GF, UL94 V-0, HF, BLACK
 - 1.2 CONTACT: COPPER ALLOY, t=0.25
 - 1.3 SHELL: METAL, t=0.30
2. PLATING:
- 2.1 CONTACT: G/F ON CONTACT AREA, MATTE TIN ON SOLDER TAILS, NICKEL UNDERPLATING OVER ALL
 - 2.2 SHELL: 50u" MIN. NICKEL OVER ALL
3. MECHANICAL CHARACTERISTIC
- Mating Force: 35N(3.57kgf) max.
- Unmating Force: 9.8N(1kgf) min.
- Durability: 5000 Cycles.
4. ELECTRICAL CHARACTERISTIC
- Contact Resistance: 30m Ohm Max.
- Insulation Resistance: 1000M Ohm Min
- Dielectric Withstanding Voltage: 500V AC Min
5. TEMPERATURE
- Operating Temperature: -30° C~+85° C
- Storage Temperature: -60° C~+105° C
6. PRODUCT No. DESCRIPTION:
- WUSF12504-0A00B

3	SHELL	1	METAL	50u" MIN. NICKEL PLATED
2	CONTACT	4	COPPER ALLOY	1u" AU PLATED ON CONTACT AREA 80u" MATTE TIN PLATED ON SOLDER TAILS
1	HOUSING	1	LCP	BLACK
ITEM	DESCRIPTION	QUA'T	MATERIAL	REMARK

REV.	REVISION RECORD	DATE	GENERAL TOLERANCES		SCALE: NA	NAME	DATE	TITLE:		PART NO:
X1	WN-2106240004 NEW REVISION	2021.06.23	LINEAR	ANGLES	APPROVED			广东富盈兴业精密科技实业有限公司		WUSF12504-0A00B
			UNIT: MM	X° ± 5°	DESIGNER			USB2.0 AP STD CH=4.20 H=7.06		DWG.NO:
			SIZE: A4	0.00±0.20	DRAWN			REV: X1	SHEET: 1/2	
				0.000±0.10						
				.X° ± 3°						
				.X° ± 2°						